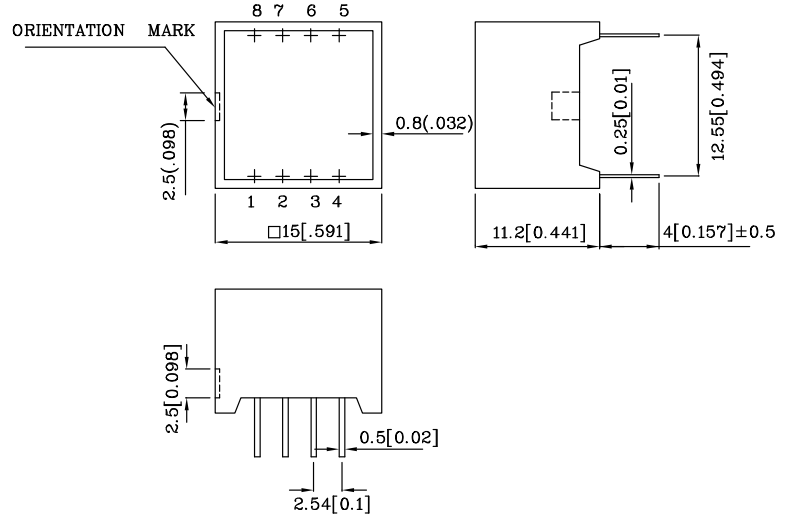
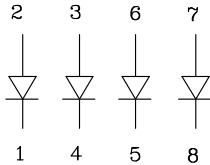


Features

- UNIFORM LIGHT EMITTING AREA.
- EASILY MOUNTED ON P.C. BOARDS OR INDUSTRY STANDARD SOCKETS.
- FLUSH MOUNTABLE.
- EXCELLENT ON/OFF CONTRAST.
- CAN BE USED WITH PANELS AND LEGEND MOUNTS.
- MECHANICALLY RUGGED.
- I.C. COMPATIBLE.
- RoHS COMPLIANT.



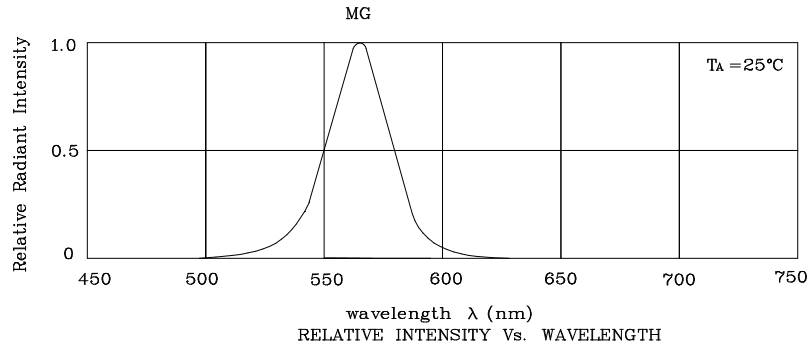
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

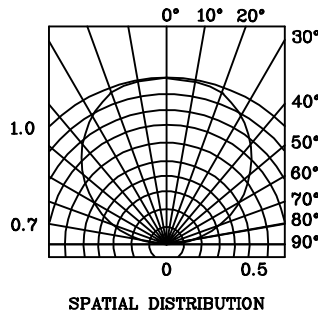
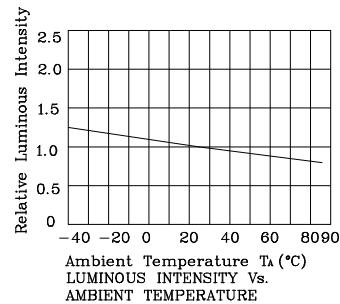
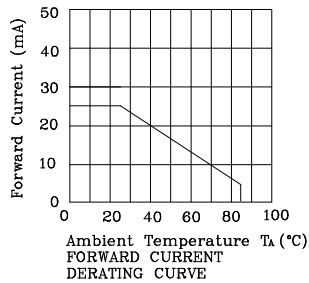
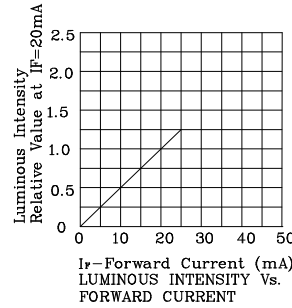
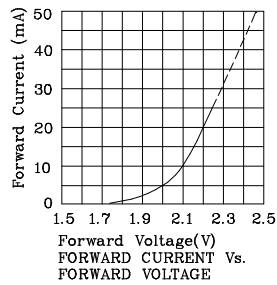
Absolute maximum ratings (TA=25°C)		MG (GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	140	mA
Power Dissipation	P _T	105	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		MG (GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	2.2	V
Forward Voltage (Max.) (I _F =20mA)	V _F	2.5	V
Reverse Current (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (I _F =20mA)	λ P	565	nm
Wavelength of Dominant Emission (I _F =20mA)	λ D	568	nm
Spectral Line Full Width At Half-Maximum (I _F =20mA)	Δλ	30	nm
Capacitance (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XEMG29DX	Green	GaP	Green Diffused	18	79	565	120°
Published Date : MAY 28,2005 Drawing No : XDSA1965 V3 Checked : Shin Chi P.1/3							



❖ MG



Remarks:

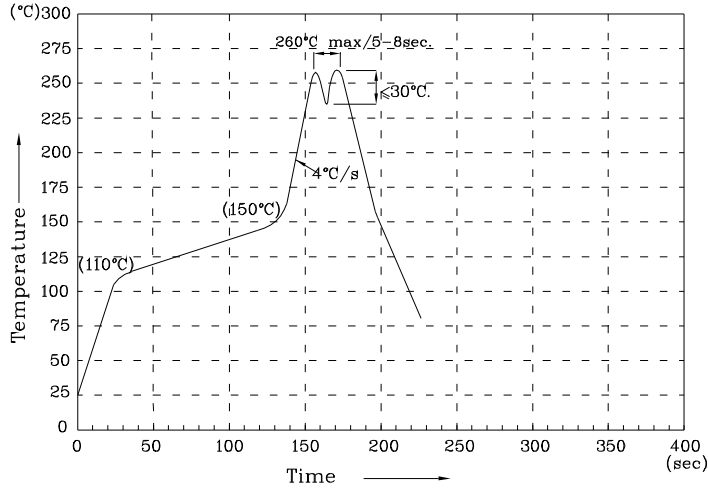
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XEMG29DX

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.